

DEVICE TESTING APPARATUS

This application is a continuation of co-pending Application No.

10/121,592, filed on April 15, 2002, which is a divisional of Application No.

5 09/448,303, filed on November 24, 1999, now abandoned, the entire contents of  
which are hereby incorporated by reference and for which priority is claimed under  
35 U.S.C. § 120; and this application claims priority of Application Nos. 10-  
333,864 filed in Japan on November 25, 1998, 10-364,356 filed in Japan on  
December 22, 1998, and 10-351,357 filed in Japan on December 10, 1998 under 35

10 U.S.C. § 119.

**BACKGROUND OF THE INVENTION****1. Field of the Invention**

The present invention relates to a device testing apparatus for testing IC  
chips and other electronic devices at a predetermined temperature, more  
15 particularly relates to a device testing apparatus which accurately controls the  
temperature of the electronic devices even if the electronic devices generate heat on  
their own during the testing and thereby enables the electronic devices to be tested  
at the desired test temperature.

**2. Description of the Related Art**

20 In the process of production of a semiconductor device etc., a tester is  
necessary for testing the finally produced IC chip or other device. As one type of  
such a tester, there is known an apparatus for testing an IC chip at high  
temperature, ordinary temperature or temperature conditions lower than ordinary  
temperature. This is because it is guaranteed as one of the features of an IC chip  
25 that it operate well as high temperature, ordinary temperature, or low temperature.

In such a tester, the top of the test head is covered by a chamber,  
the inside is made an air-tight space, an IC chip is coveyed on to the test  
head, the IC chip is pushed against the test head for connection, and the  
IC chip is tested while maintaining the inside of the chamber at a certain